US00D877103S

(12) **United States Design Patent** (10) **Patent No.: US D877,103 S**
Venk et al. (45) **Date of Patent: ** Mar. 3, 2020**

(54) **CONDUCTOR PAD**

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(**) Term: **15 Years**

(21) Appl. No.: **29/680,129**

(22) Filed: **Feb. 13, 2019**

Related U.S. Application Data

(62) Division of application No. 29/584,216, filed on Nov. 12, 2016, now Pat. No. Des. 844,577, which is a (Continued)

(51) **LOC (12) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/133, 182; 324/754.01, 754.02, 324/754.03; 361/19, 107, 637, 515, 813;
(Continued)

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D328,599 S	*	8/1992	Gloton	D13/182

(Continued)

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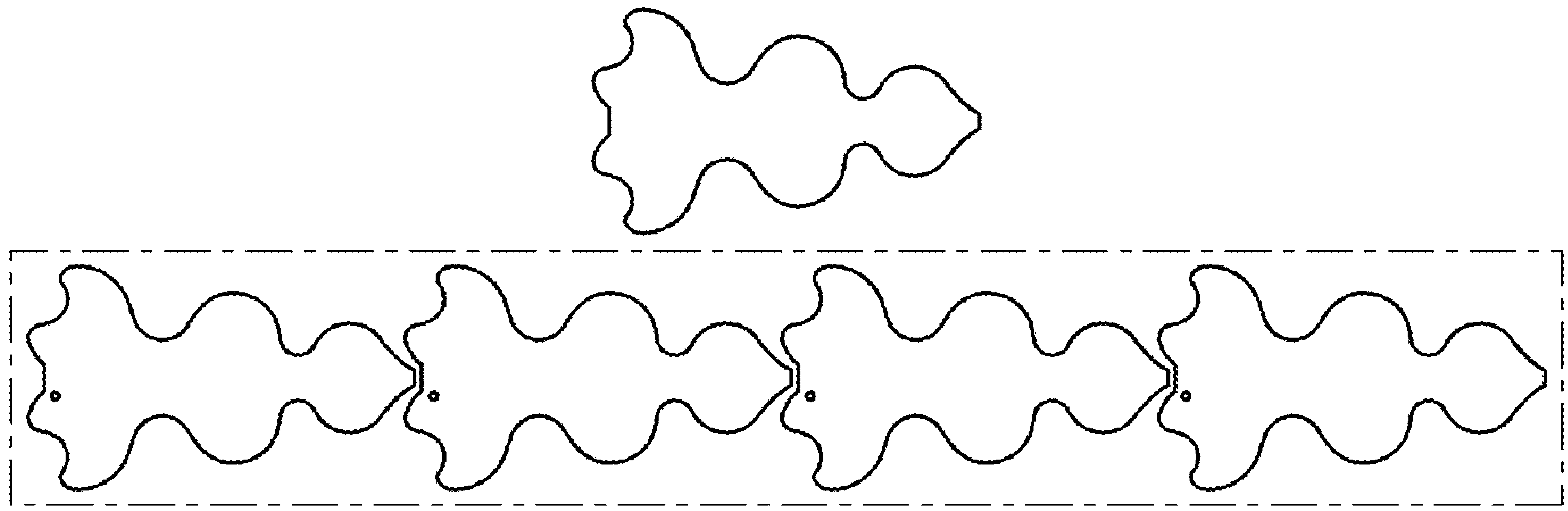
(57) **CLAIM**

The ornamental design for a conductor pad, as shown and described.

DESCRIPTION

FIG. **1** is a top plan view of a first embodiment of a conductor pad showing our new design, the bottom plan view being a mirror image thereof.
FIG. **2** is a top plan view of a second embodiment of a conductor pad showing our new design, the bottom plan view being a mirror image thereof.
FIG. **3** is a top plan view of a third embodiment of a conductor pad showing our new design, the bottom plan view being a mirror image thereof.
FIG. **4** is a top plan view of a fourth embodiment of a conductor pad showing our new design, the bottom plan view being a mirror image thereof.
FIG. **5** is a top plan view of a fifth embodiment of a conductor pad showing our new design, the bottom plan view being a mirror image thereof.
FIG. **6** is a top plan view of a sixth embodiment of a conductor pad showing our new design, the bottom plan view being a mirror image thereof.
FIG. **7** is a top plan view of a seventh embodiment of a conductor pad showing our new design, the bottom plan view being a mirror image thereof.
FIG. **8** is a top plan view of an eighth embodiment of a conductor pad showing our new design, the bottom plan view being a mirror image thereof.
FIG. **9** is a top plan view of a ninth embodiment of a conductor pad showing our new design, the bottom plan view being a mirror image thereof.
FIG. **10** is a top plan view of a tenth embodiment of a conductor pad showing our new design, the bottom plan view being a mirror image thereof.
FIG. **11** is a top plan view of an eleventh embodiment of a conductor pad showing our new design, the bottom plan view being a mirror image thereof; and,
FIG. **12** is a top plan view of a twelfth embodiment of a conductor pad showing our new design, the bottom plan view being a mirror image thereof.
The broken-line disclosure in the views is understood to represent portions of the article in which the claimed design is embodied, but which form no part of the claimed design. All surfaces not shown form no part of the claimed design.

1 Claim, 3 Drawing Sheets



Related U.S. Application Data

division of application No. 29/486,410, filed on Mar. 28, 2014, now Pat. No. Des. 774,477.

(58) **Field of Classification Search**

USPC 439/43, 52, 66, 12, 208, 210, 456, 457, 439/458, 902; 438/614, 610, 584, 612, 438/618

CPC ... H01L 24/03; H01L 24/05; H01L 23/49575; H01L 24/34; H01L 2224/05556; H01J 37/08; H01J 37/26; G01N 23/00

See application file for complete search history.

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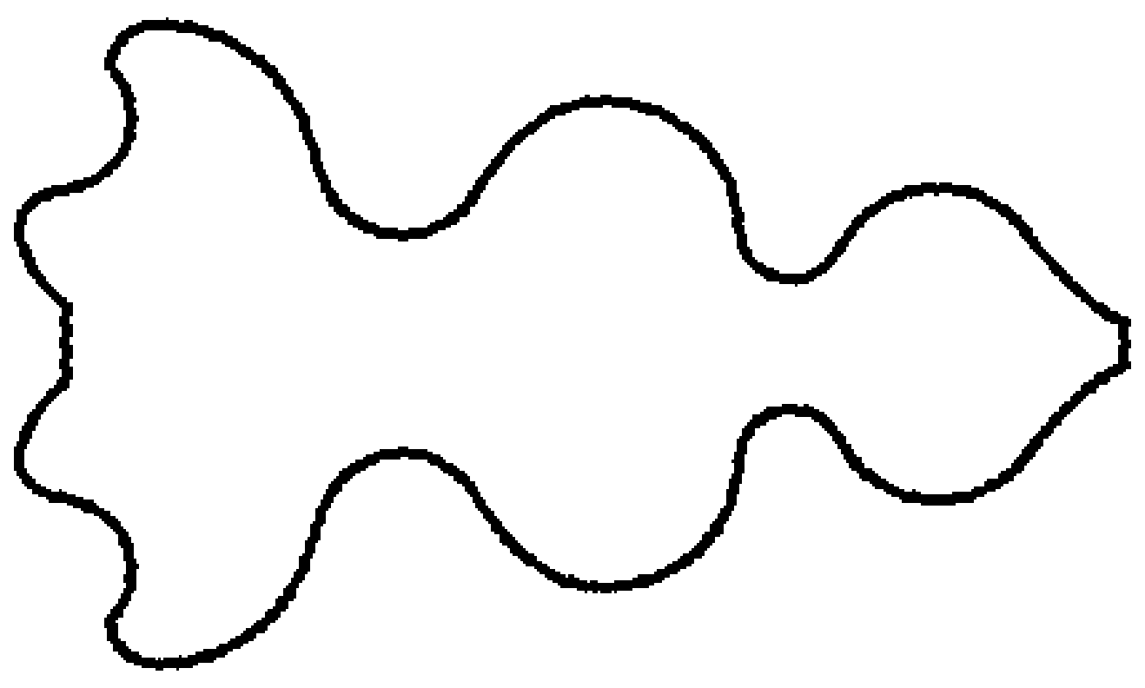

FIG. 1

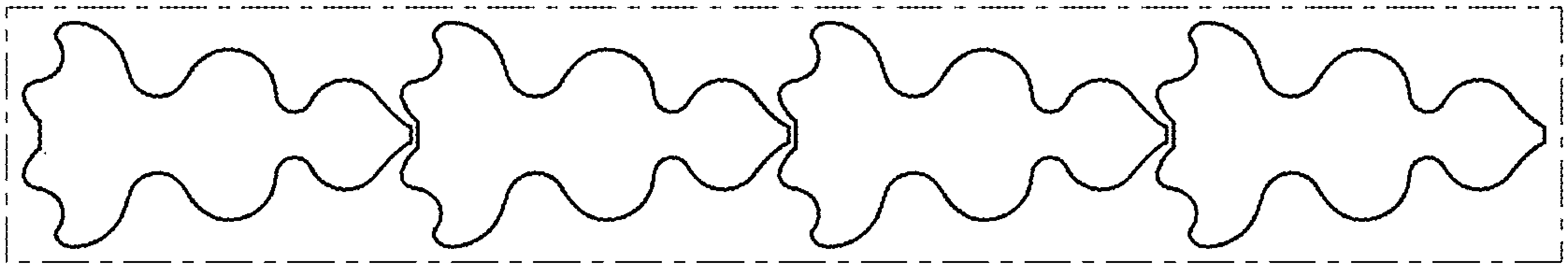

FIG. 2

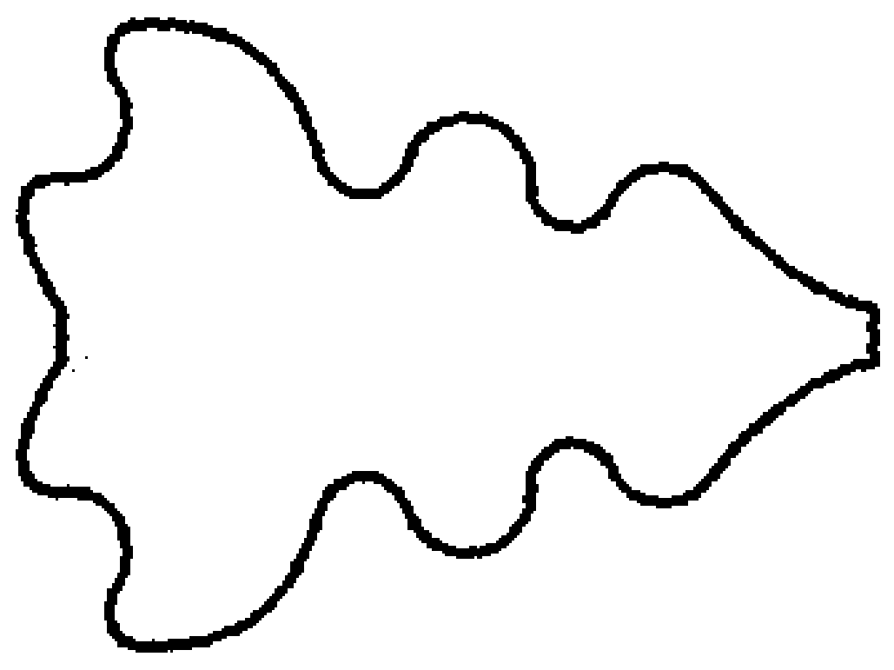

FIG. 3

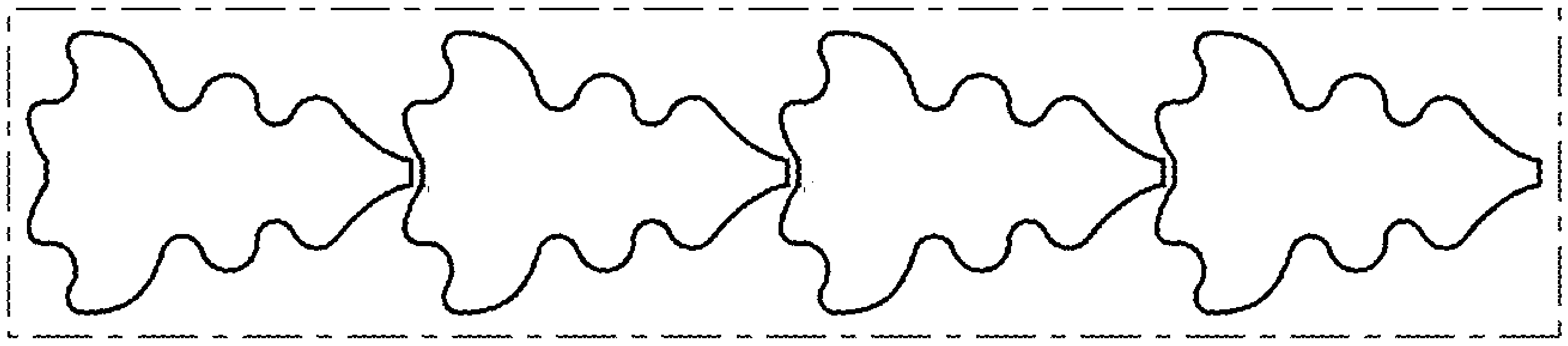

FIG. 4

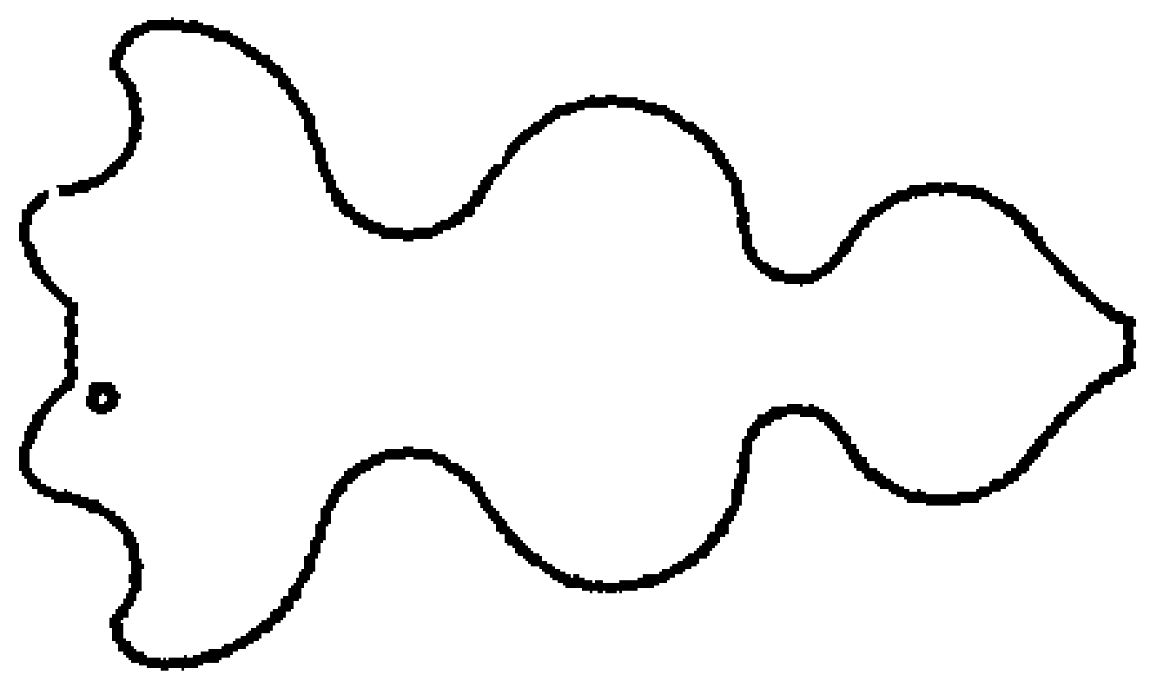

FIG. 5

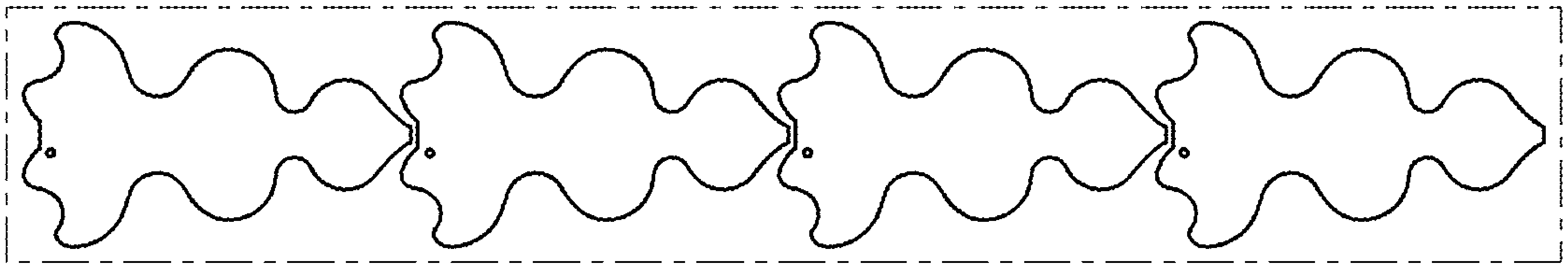

FIG. 6

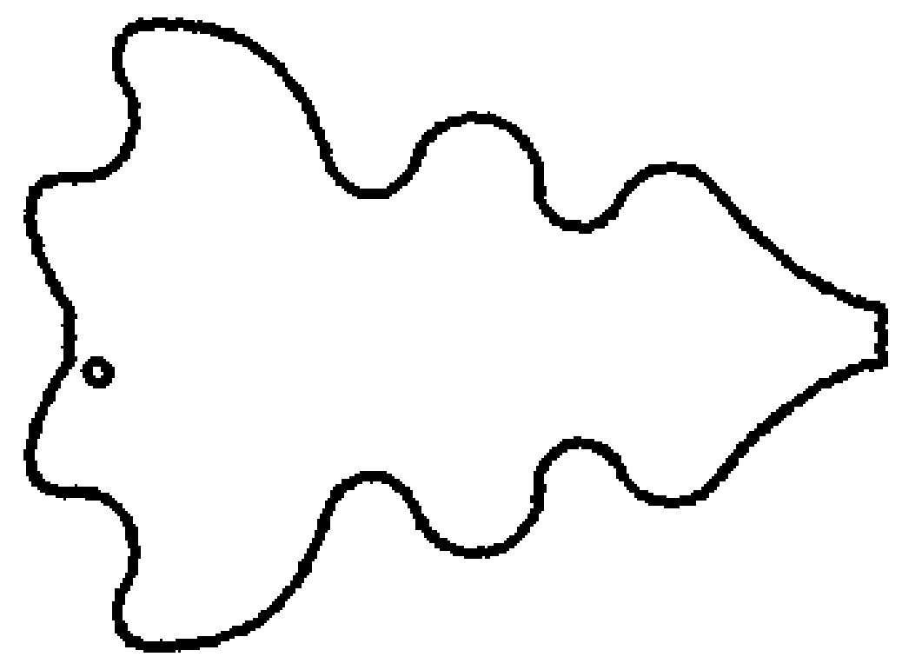

FIG. 7

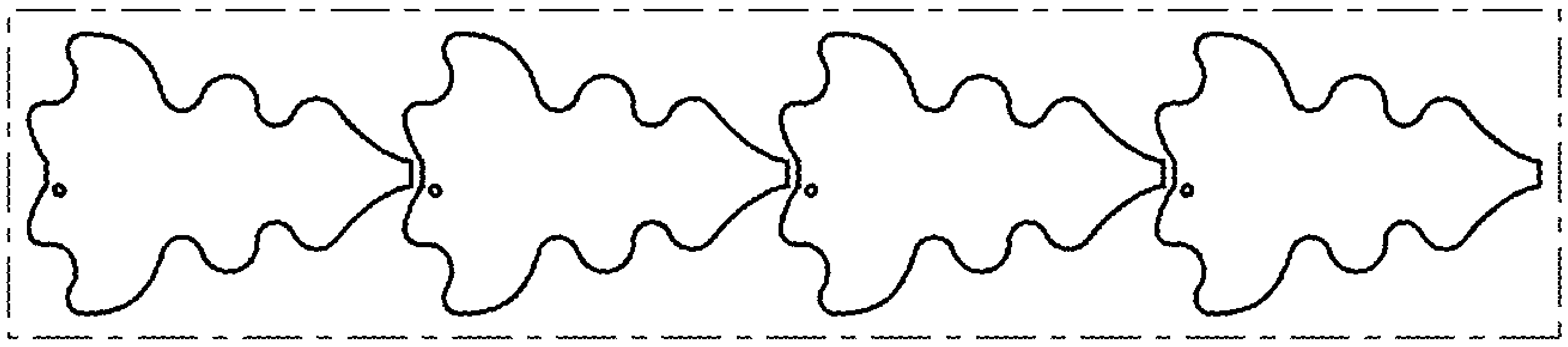

FIG. 8

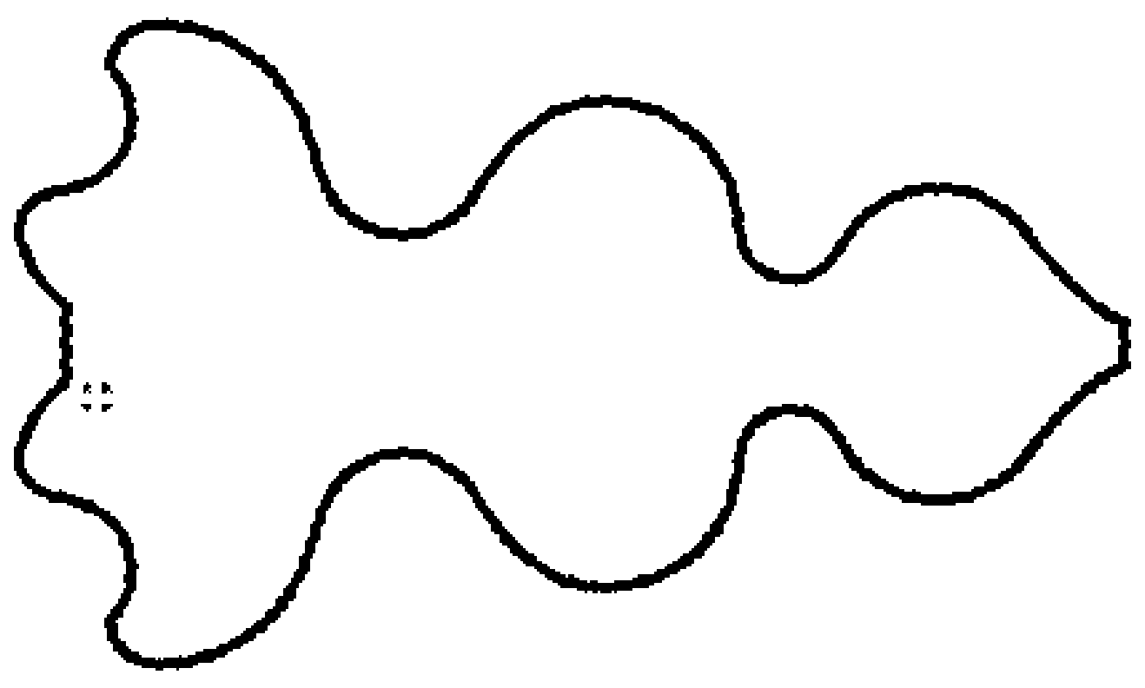

FIG. 9

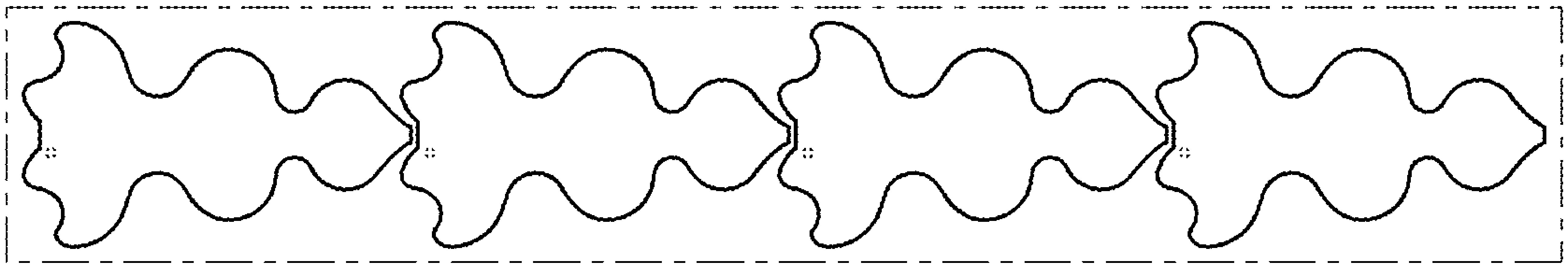

FIG. 10

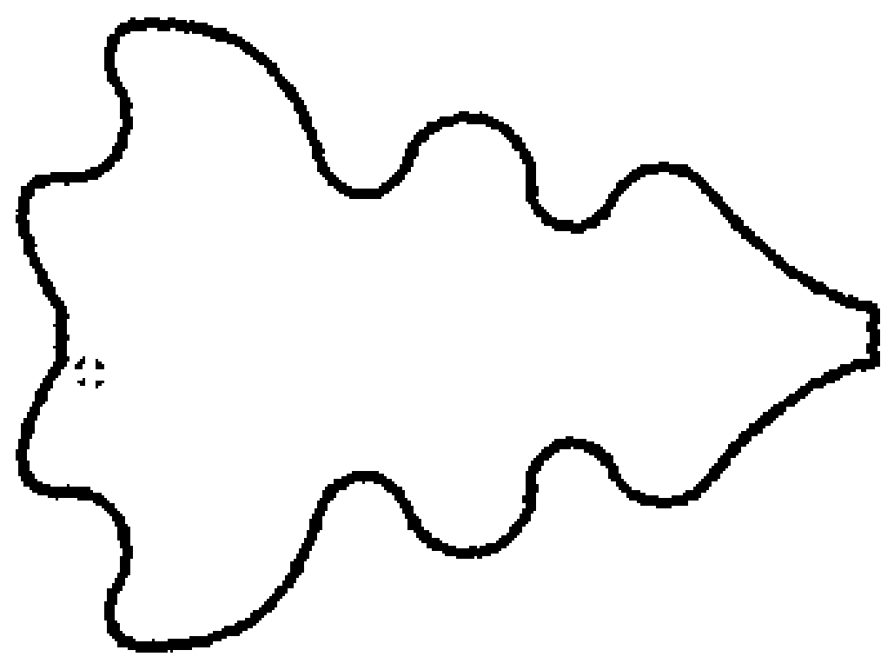

FIG. 11

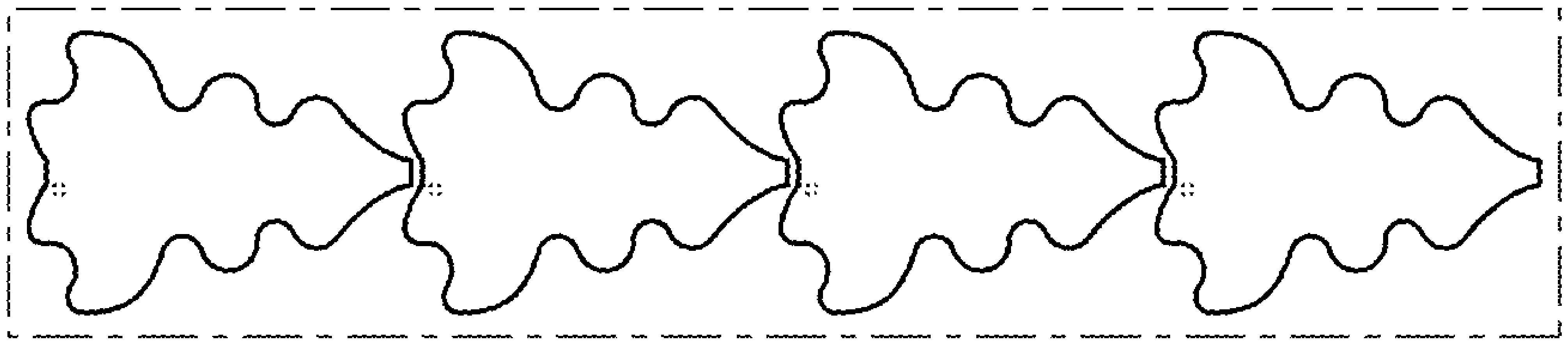

FIG. 12